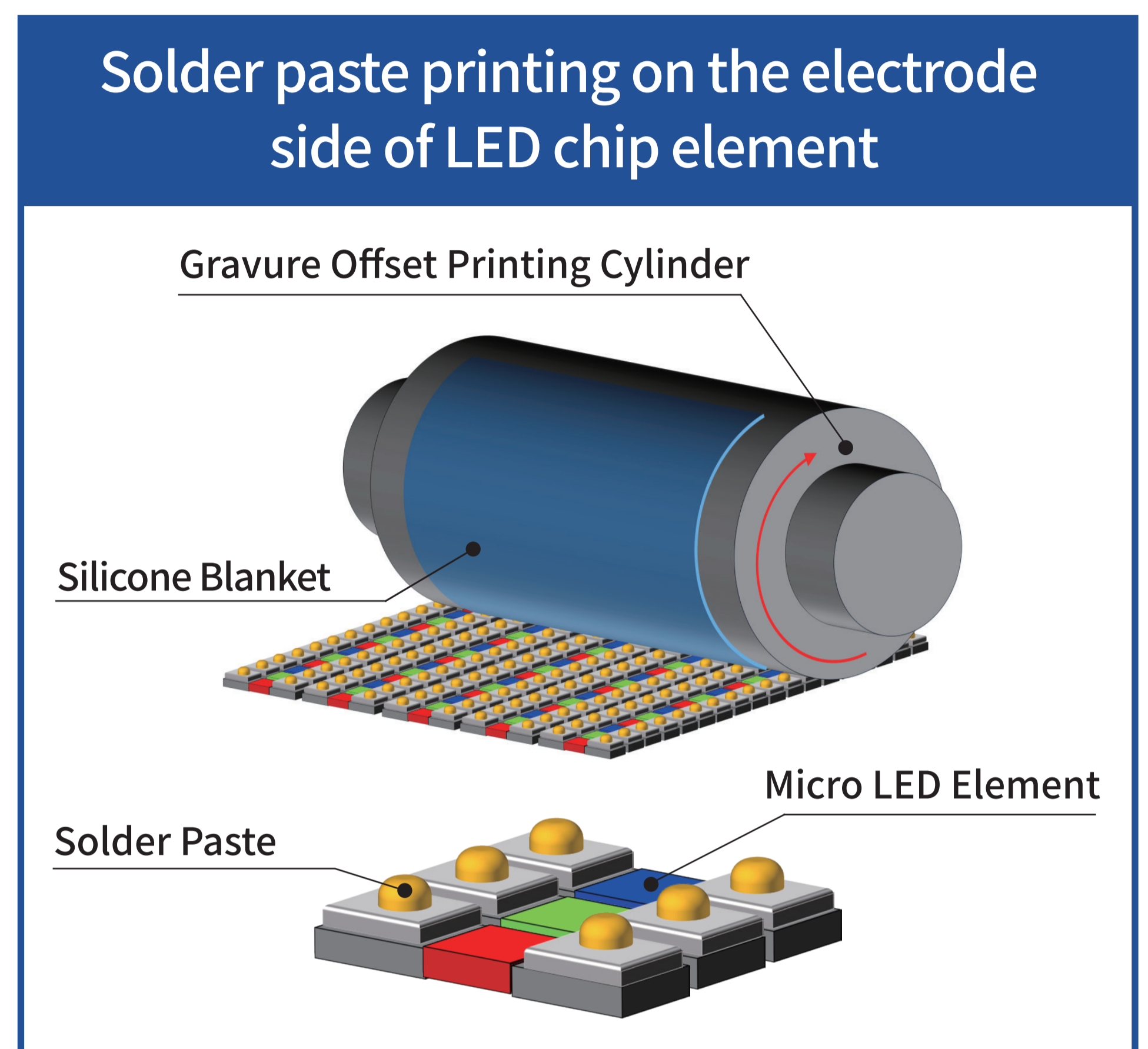
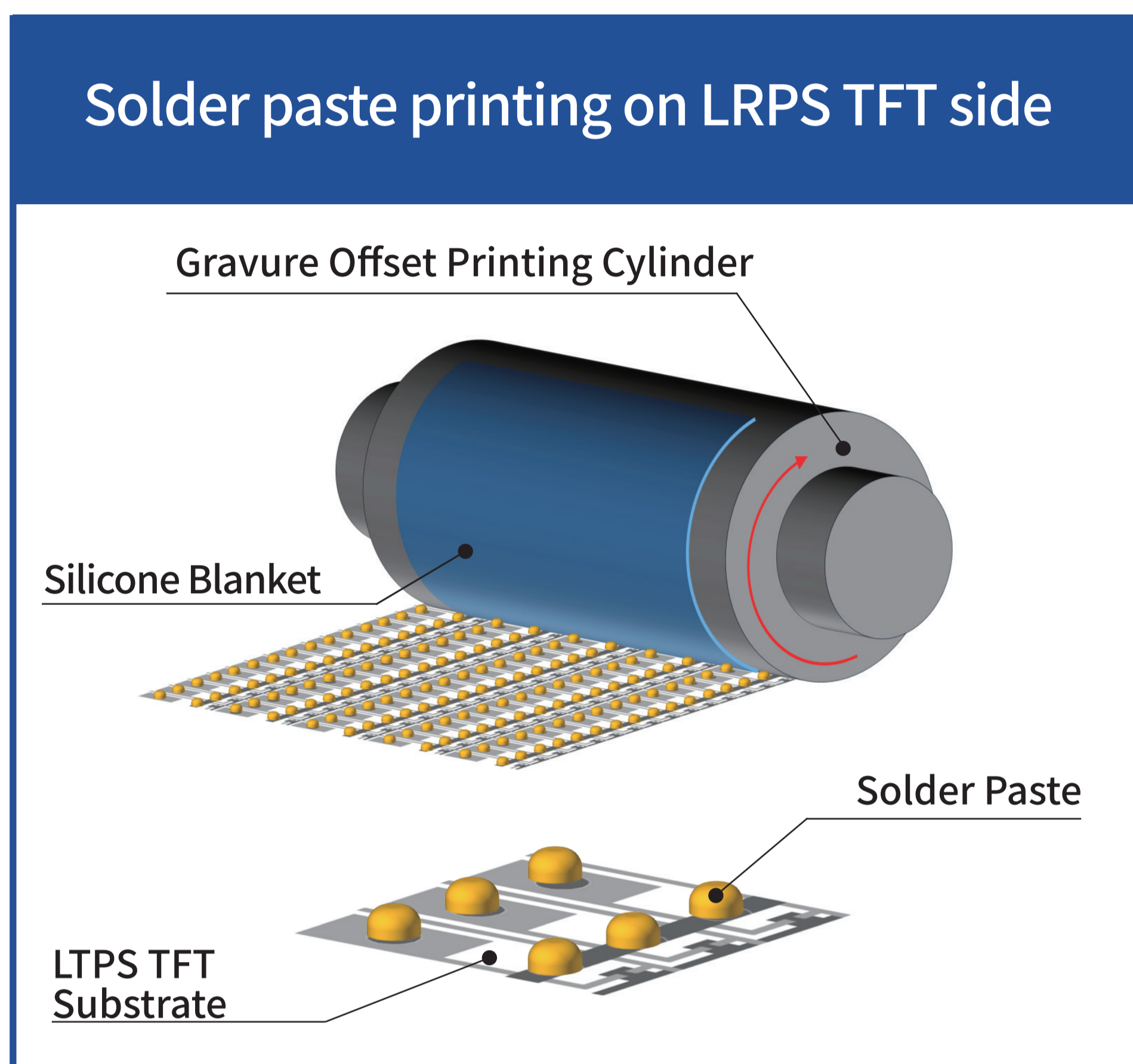


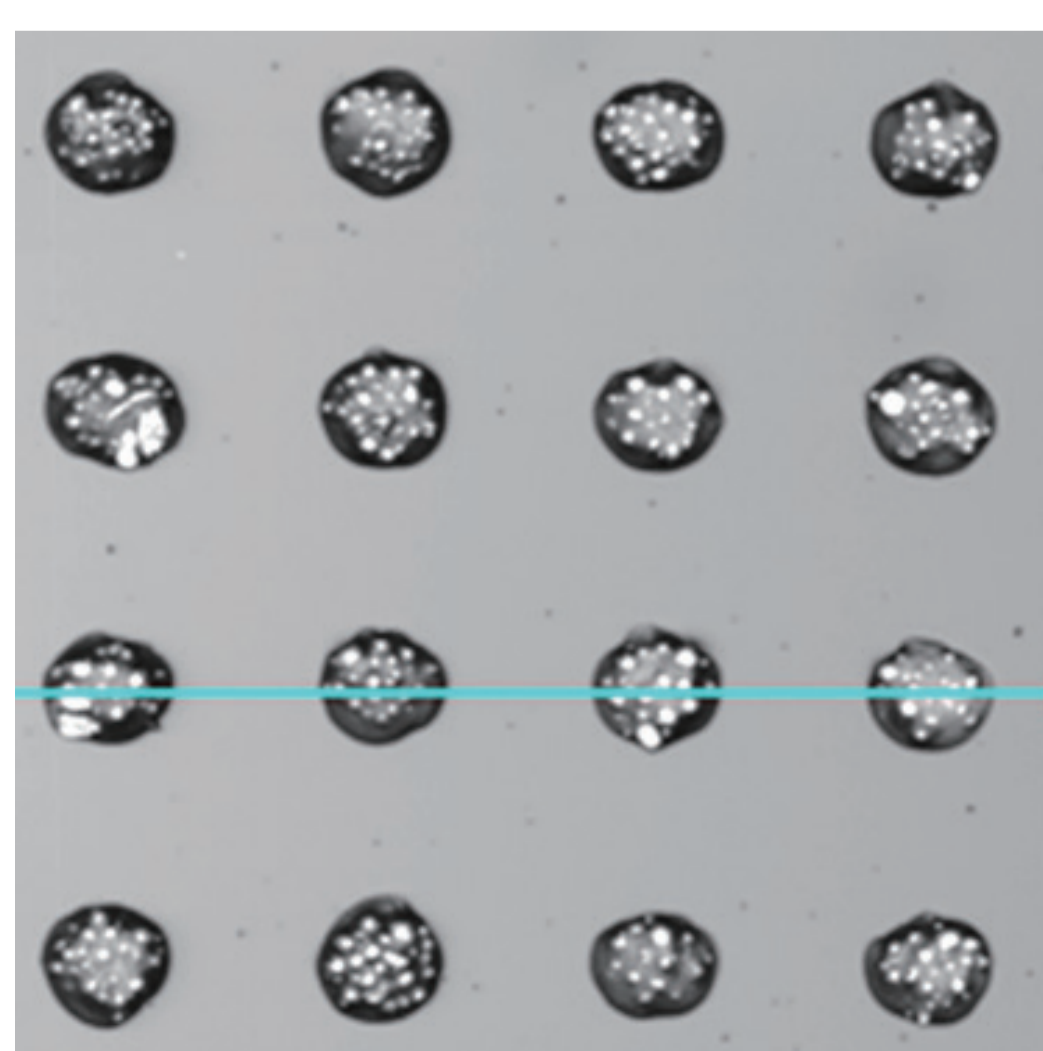
Gravure Offset Bonding Technology

We have achieved printing fine solder paste by taking advantage of the fine thin line and high precision that are the characteristics of gravure offset printing. We propose this performance for bonding micro LEDs and small components.

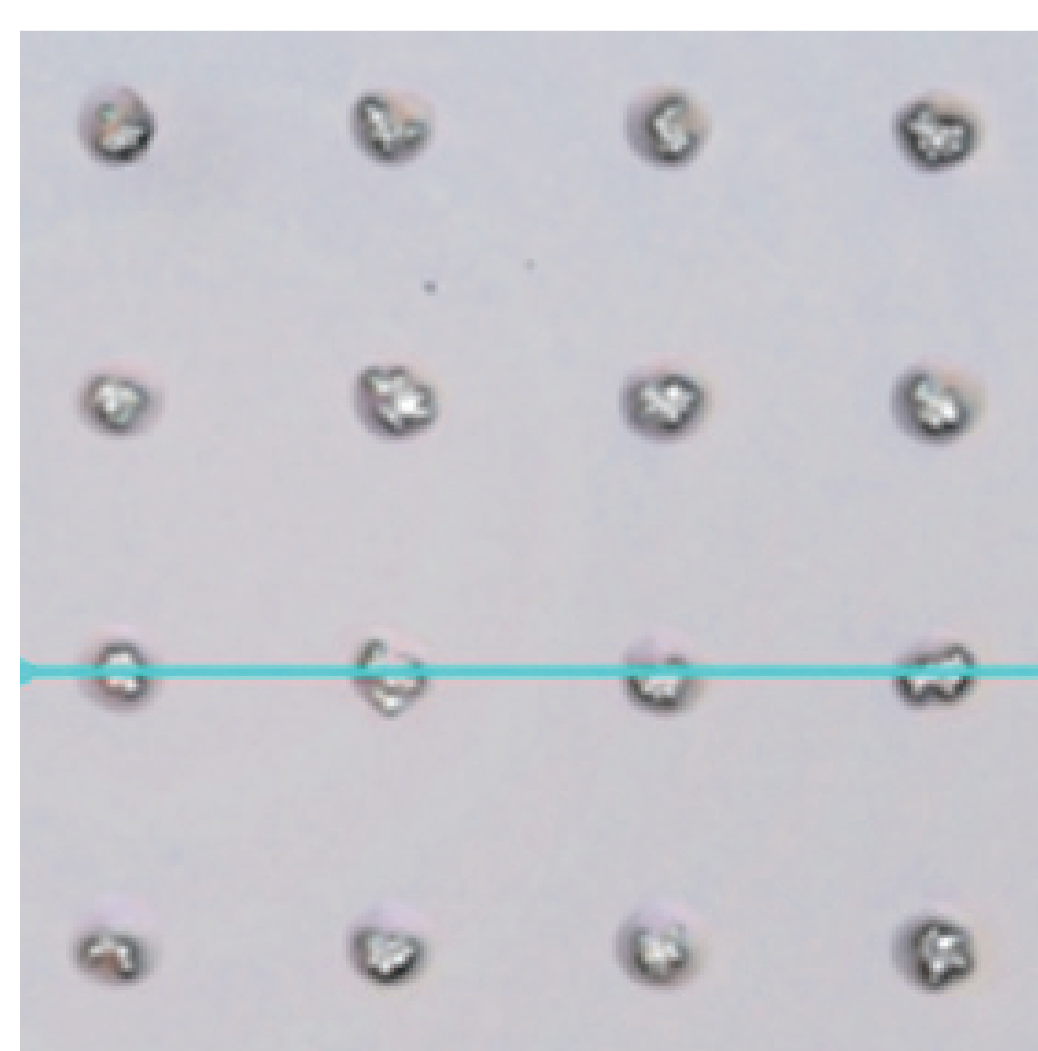


The minimum printable diameter depends on the solder particle size. We will respond to your requests using our plate-making technology and new fine solder paste.

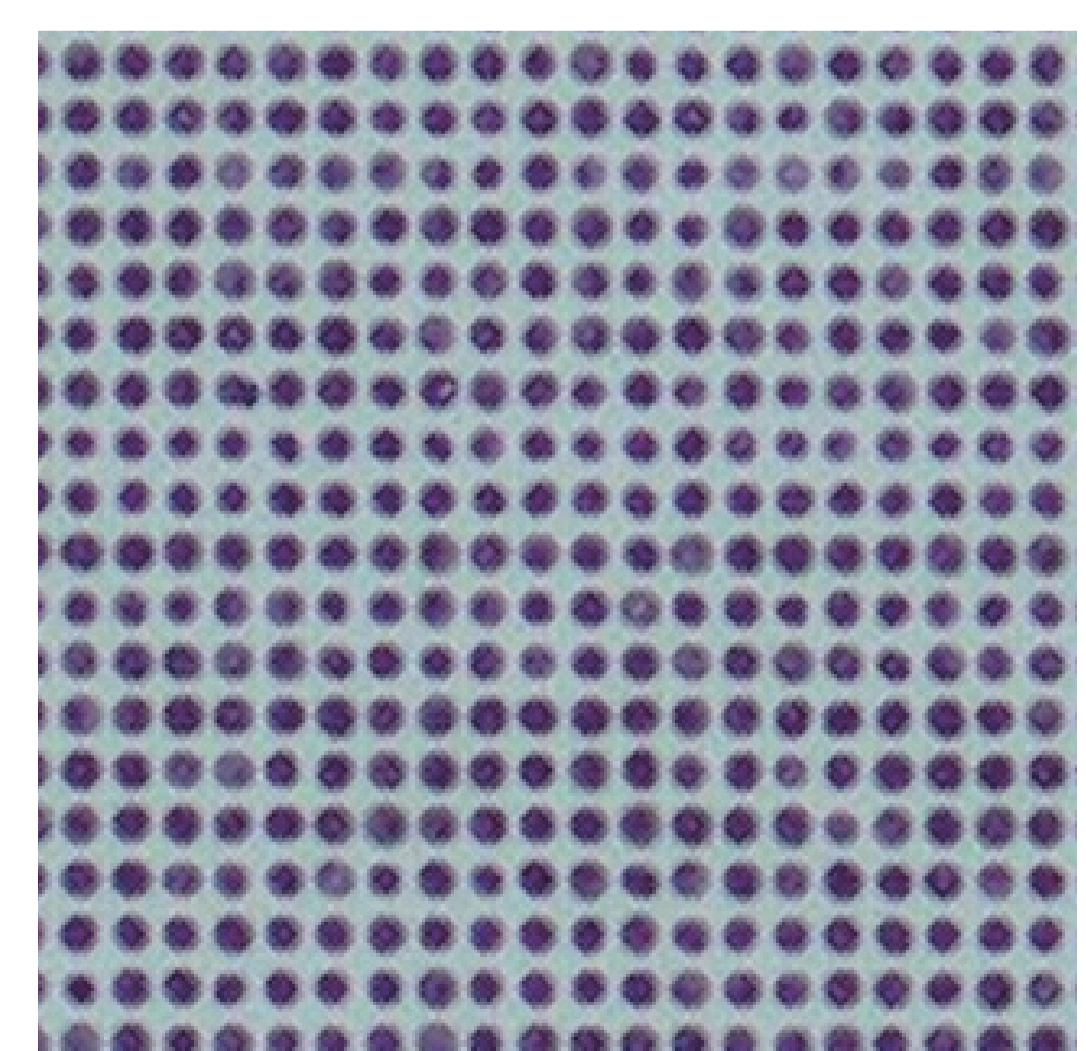
| solder paste | Type Ave or D50 Size range (μm) | Type4 $\Phi 25\mu\text{m}$ 20-38 | Type5 $\Phi 18\mu\text{m}$ 15-25 | Type6 $\Phi 11\mu\text{m}$ 5-15 | Type7 $\Phi 8\mu\text{m}$ 2-11 | Type8 $\Phi 5\mu\text{m}$ 1-8 | Type9 about $\Phi 3\mu\text{m}$ about 1-5 | smaller Under development |
|--------------|--|--|--|---------------------------------------|--------------------------------------|-------------------------------------|---|------------------------------|
| Application | SMT use | █ | | | | | | |
| | High Density Interconnect (HDI) | | █ | | | | | |
| | Substrate-like-PCB (SLP) | | █ | | | | | |
| | System in Package (SIP) | | | █ | | | | |
| | Mini Micro LED | | | | | █ | | |



$\Phi 20\mu\text{m}$



$\Phi 10\mu\text{m}$



narrow pitch $\Phi 8\mu\text{m}/\text{gap}8\mu\text{m}$